

HD74LV273A

Octal D-type Flip-Flops with Clear

REJ03D0330-0300Z (Previous ADE-205-273A (Z)) Rev.3.00 Jun. 25, 2004

Description

The HD74LV273A has eight edges trigger D-type flip-flops with clear in a 20-pin package. Data on the D input having the specified setup and hold times is transferred to the Q output on the low to high transition of the clock input. The clear input when low sets all outputs to a low state. Low-voltage and high-speed operation is suitable for battery-powered products (e.g., notebook computers), and the low-power consumption extends the battery life.

Features

- $V_{CC} = 2.0 \text{ V to } 5.5 \text{ V operation}$
- All inputs V_{IH} (Max.) = 5.5 V (@ V_{CC} = 0 V to 5.5 V)
- All outputs V_0 (Max.) = 5.5 V (@ V_{CC} = 0 V)
- Typical V_{OL} ground bounce < 0.8 V (@ V_{CC} = 3.3 V, Ta = 25°C)
- Typical V_{OH} undershoot > 2.3 V (@ V_{CC} = 3.3 V, Ta = 25°C)
- Output current ± 6 mA (@V_{CC} = 3.0 V to 3.6 V), ± 12 mA (@V_{CC} = 4.5 V to 5.5 V)

Ordering Information

Part Name	Package Type	Package Code	Package Abbreviation	Taping Abbreviation (Quantity)
HD74LV273AFPEL	SOP-20 pin (JEITA)	FP-20DAV	FP	EL (2,000 pcs/reel)
HD74LV273ARPEL	SOP-20 pin (JEDEC)	FP-20DBV	RP	EL (1,000 pcs/reel)
HD74LV273ATELL	TSSOP-20 pin	TTP-20DAV	Т	ELL (2,000 pcs/reel)

Note: Please consult the sales office for the above package availability.

Function Table

Inputs

CLR	CLK	D	Output Q
L	X	X	L
Н	\uparrow	Н	Н
Н	\uparrow	L	L
Н	\downarrow	X	Q_0

Note: H: High level

L: Low level

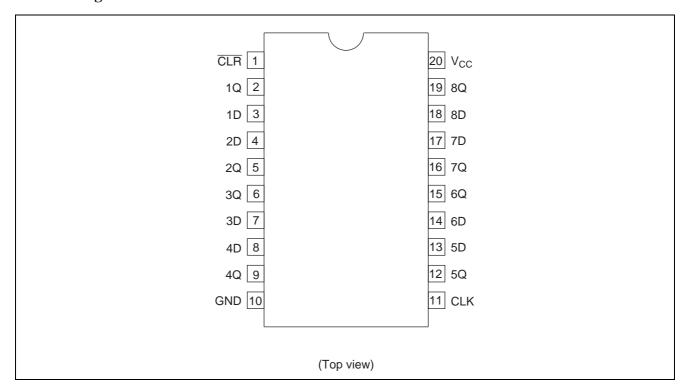
X: Immaterial

↑: Low to high transition

↓: High to low transition

Q₀: Output level before the indicated steady state input conditions were established.

Pin Arrangement



Absolute Maximum Ratings

Item	Symbol	Ratings	Unit	Conditions
Supply voltage range	V_{CC}	-0.5 to 7.0	V	
Input voltage range*1	Vı	-0.5 to 7.0	V	
Output voltage range*1,2	Vo	-0.5 to $V_{CC} + 0.5$	V	Output: H or L
		-0.5 to 7.0		V _{CC} : OFF
Input clamp current	I _{IK}	-20	mA	V ₁ < 0
Output clamp current	lok	±50	mA	$V_O < 0$ or $V_O > V_{CC}$
Continuous output current	lo	±25	mA	$V_O = 0$ to V_{CC}
Continuous current through	I _{CC} or I _{GND}	±50	mA	
V _{CC} or GND				
Maximum power dissipation at	P _T	835	mW	SOP
Ta = 25°C (in still air)*3		757		TSSOP
Storage temperature	Tstg	-65 to 150	°C	

Notes: The absolute maximum ratings are values, which must not individually be exceeded, and furthermore, no two of which may be realized at the same time.

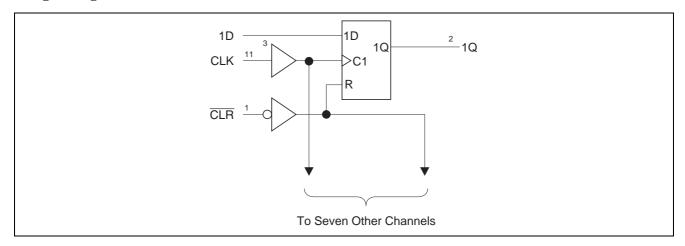
- 1. The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
- 2. This value is limited to 5.5 V maximum.
- 3. The maximum package power dissipation was calculated using a junction temperature of 150 $^{\circ}$ C.

Recommended Operating Conditions

Item	Symbol	Min	Max	Unit	Conditions
Supply voltage range	Vcc	2.0	5.5	V	
Input voltage range	Vı	0	5.5	V	
Output voltage range	Vo	0	V _{CC}	V	H or L
Output current	I _{OH}	_	-50	μΑ	V _{CC} = 2.0 V
		_	-2	mA	V _{CC} = 2.3 to 2.7 V
		_	-6		V _{CC} = 3.0 to 3.6 V
		_	-12		V _{CC} = 4.5 to 5.5 V
	I _{OL}	_	50	μΑ	V _{CC} = 2.0 V
		_	2	mA	V _{CC} = 2.3 to 2.7 V
		_	6		V _{CC} = 3.0 to 3.6 V
		_	12		V _{CC} = 4.5 to 5.5 V
Input transition rise or fall rate	Δt /Δν	0	200	ns/V	V _{CC} = 2.3 to 2.7 V
		0	100		V _{CC} = 3.0 to 3.6 V
		0	20		V _{CC} = 4.5 to 5.5 V
Operating free-air temperature	Та	-40	85	°C	

Note: Unused or floating inputs must be held high or low.

Logic Diagram



DC Electrical Characteristics

 $Ta = -40 \text{ to } 85^{\circ}\text{C}$

Item	Symbol	V _{CC} (V)	Min	Тур	Max	Unit	Test Conditions
Input voltage	V _{IH}	2.0	1.5	_	_	V	
		2.3 to 2.7	$V_{CC} \times 0.7$	_	_		
		3.0 to 3.6	$V_{\text{CC}} \times 0.7$	_	_		
		4.5 to 5.5	$V_{\text{CC}} \times 0.7$	_	_		
	V _{IL}	2.0	_	_	0.5		
		2.3 to 2.7	_	_	$V_{\text{CC}}\!\times\!0.3$		
		3.0 to 3.6	_	_	$V_{\text{CC}}\!\times\!0.3$		
		4.5 to 5.5	_	_	$V_{\text{CC}}\!\times\!0.3$		
Output voltage	V_{OH}	Min to Max	V _{CC} – 0.1	_	_	V	$I_{OH} = -50 \mu A$
		2.3	2.0	_	_		$I_{OH} = -2 \text{ mA}$
		3.0	2.48	_	_		$I_{OH} = -6 \text{ mA}$
		4.5	3.8	_	_		$I_{OH} = -12 \text{ mA}$
	V _{OL}	Min to Max	_	_	0.1		$I_{OL} = 50 \mu A$
		2.3	_	_	0.4		I _{OL} = 2 mA
		3.0	_	_	0.44		I _{OL} = 6 mA
		4.5	_	_	0.55		I _{OL} = 12 mA
Input current	I _{IN}	0 to 5.5	_	_	±1	μΑ	$V_I = 5.5 \text{ V or GND}$
Quiescent supply	I _{CC}	5.5	_	_	20	μΑ	$V_I = V_{CC}$ or GND, $I_O = 0$
current							
Output leakage	I_{OFF}	0	_	_	5	μΑ	V_1 or $V_0 = 0$ V to 5.5 V
current							
Input capacitance	C _{IN}	3.3	_	2	_	pF	$V_I = V_{CC}$ or GND

Note: For conditions shown as Min or Max, use the appropriate values under recommended operating conditions.

Switching Characteristics

 $V_{CC}=2.5\pm0.2\ V$

		Ta =	25°C		Ta = -40) to 85°C		Test	FROM	то
Item	Symbol	Min	Тур	Max	Min	Max	Unit	Conditions	(Input)	(Output)
Maximum clock	fmax	55	95	_	45	_	MHz	C _L = 15 pF		_
frequency		45	75	_	40	_	_	C _L = 50 pF	_	
Propagation	t _{PHL}	_	10.3	19.0	1.0	21.0	ns	C _L = 15 pF	CLR	Q
delay time	t _{PLH} /t _{PHL}	_	10.4	18.3	1.0	20.5	_		CLK	Q
	t _{PHL}	_	13.1	22.8	1.0	25.5	_	C _L = 50 pF	CLR	Q
	t _{PLH} /t _{PHL}	_	12.9	22.1	1.0	25.0	_		CLK	Q
Setup time	t _{SU}	8.5	_	_	10.5	_	ns		Data	
		4.0	_	_	4.0	_	_		CLR inac	tive
Hold time	t _h	0.5	_	_	1.0	_	ns			
Pulse width	t _W	6.5	_	_	7.0	_	ns		CLR L	
		7.0	_	_	8.5	_	_		CLK H or	· L

 $V_{CC}=3.3\pm0.3~V$

		Ta =	25°C		Ta = -40	0 to 85°C		Test	FROM	то
Item	Symbol	Min	Тур	Max	Min	Max	Unit	Conditions	(Input)	(Output)
Maximum clock	fmax	75	140	_	65	_	MHz	C _L = 15 pF		
frequency		50	110	_	45	_		C _L = 50 pF		
Propagation	t _{PHL}	_	6.9	13.6	1.0	16.0	ns	$C_L = 15 pF$	CLR	Q
delay time	t _{PLH} /t _{PHL}	_	7.1	13.6	1.0	16.0			CLK	Q
	t _{PHL}	_	8.7	17.1	1.0	19.5		C _L = 50 pF	CLR	Q
	t _{PLH} /t _{PHL}	_	9.1	17.1	1.0	19.5			CLK	Q
Setup time	t _{SU}	5.5	_	_	6.5	_	ns		Data	
		2.5	_	_	2.5	_	_		CLR inac	tive
Hold time	t _h	1.0	_	_	1.0	_	ns			
Pulse width	t _W	5.0	_	_	6.0	_	ns	_	CLR L	
		5.5	_	_	6.5	_			CLK H or	L

 $V_{CC} = 5.0 \pm 0.5~V$

										CC
		Ta =	25°C		Ta = -4	40 to 85°C		Test	FROM	ТО
Item	Symbol	Min	Тур	Max	Min	Max	Unit	Conditions	(Input)	(Output)
Maximum clock	fmax	120	205	_	100	_	MHz	C _L = 15 pF		
frequency		80	160	_	70	_		C _L = 50 pF		
Propagation	t _{PHL}	_	4.7	8.5	1.0	10.0	ns	C _L = 15 pF	CLR	Q
delay time	t _{PLH} /t _{PHL}	_	4.8	9.0	1.0	10.5	_		CLK	Q
	t _{PHL}	_	6.0	10.5	1.0	12.0	_	C _L = 50 pF	CLR	Q
	t _{PLH} /t _{PHL}	_	6.2	11.0	1.0	12.5	_		CLK	Q
Setup time	t _{SU}	4.5	_	_	4.5	_	ns		Data	
		2.0	_	_	2.0	_	_		CLR inac	tive
Hold time	t _h	1.0	_	_	1.0	_	ns			
Pulse width	t _W	5.0	_	_	5.0	_	ns		CLR L	
		5.0	_		5.0	_	_		CLK H or	·L

Output-skew Characteristics

			Ta = 2	5°C	Ta = -4	40 to 85°C	
Item	Symbol	$V_{CC} = (V)$	Min	Max	Min	Max	Unit
Output skew	t _{sk (O)}	2.3 to 2.7	_	2.0	_	2.0	ns
		3.0 to 3.6	_	1.5	_	1.5	
		4.5 to 5.5	_	1.0	_	1.0	

Note: Skew between any outputs of the same package switching in the same direction. This parameter is warranted but not production tested.

Operating Characteristics

 $C_L = 50 \text{ pF}$

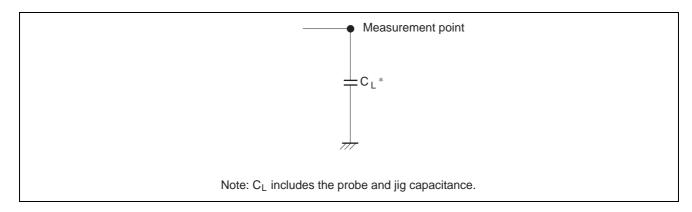
Ta = 25°C									
Item	Symbol	$V_{CC} = (V)$	Min	Тур	Max	Unit	Test Conditions		
Power dissipation capacitance	C_{PD}	3.3	_	15.9	_	pF	f = 10 MHz		
		5.0	_	17.1	_				

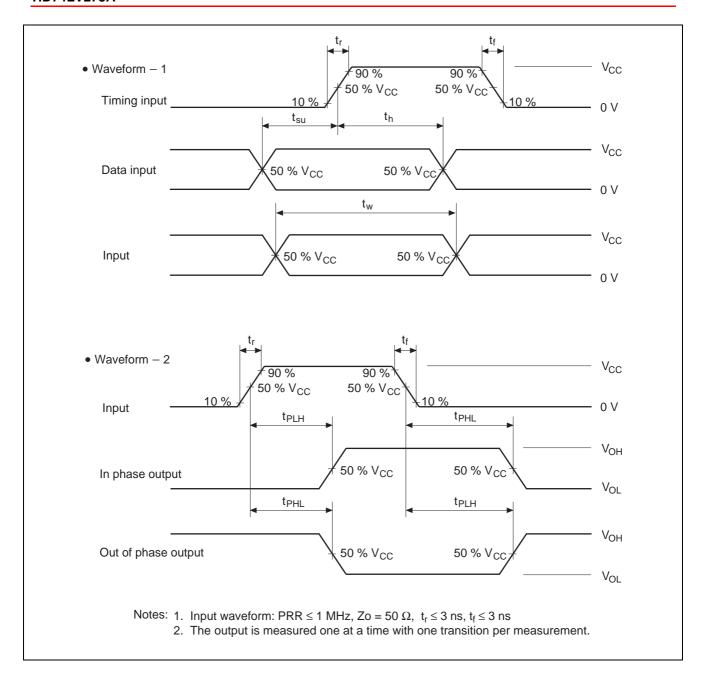
Noise Characteristics

 $C_L = 50 pF$

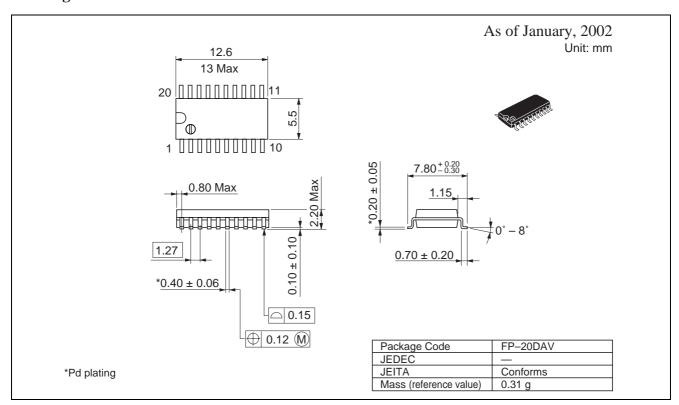
			Ta = 25	5°C			
Item	Symbol	$V_{CC} = (V)$	Min	Тур	Max	Unit	Test Conditions
Quiet output, maximum dynamic V _{OL}	V _{OL (P)}	3.3	_	0.4	0.8	V	
Quiet output, minimum dynamic V _{OL}	$V_{OL\ (V)}$	3.3	_	-0.4	-0.8	V	
Quiet output, minimum dynamic V _{OH}	V _{OH (V)}	3.3	_	2.9	_	V	
High-level dynamic input voltage	V _{IH (D)}	3.3	2.31	_	_	V	
Low-level dynamic input voltage	V _{IL (D)}	3.3	_	_	0.99	V	

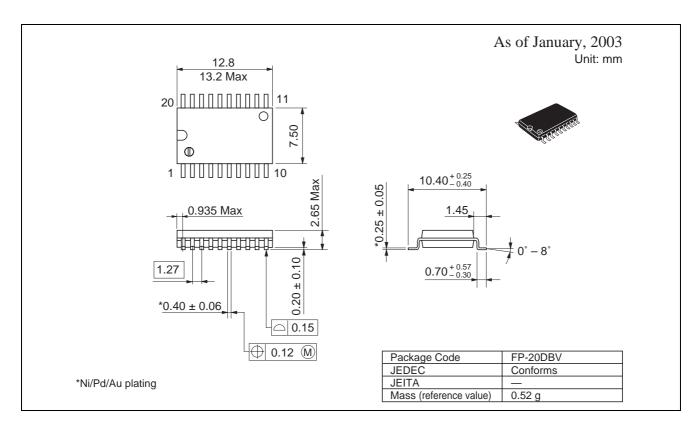
Test Circuit

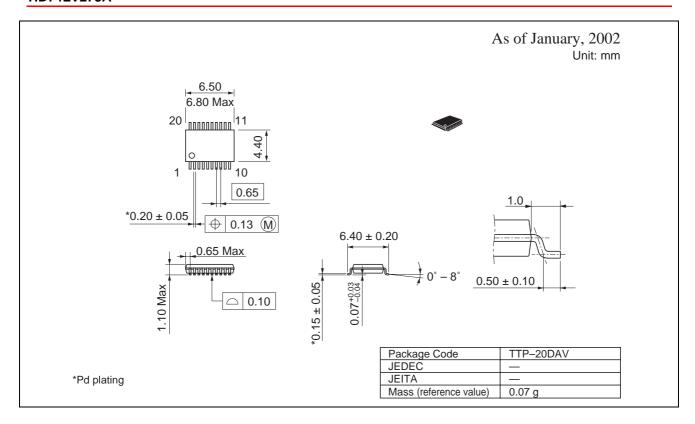




Package Dimensions







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